IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Number	:	10/595,303	Confirmation No.: 7114
Applicant	:	Roy KNECHTEL	
Filed	:	April 6, 2006	
Title	:	METHOD AND DEVICE FOR SECURE, INSULATED AND ELECTRICALLY CONDUCTIVE ASSEMBLING OF TREATED SEMICONDUCTOR WAFERS	
TC/Art Unit	:	Unassigned	
Examiner:	:	Unassigned	
Docket No.	:	60291.000048	
Customer No.	:	**21967**	

SUBMISSION OF VERIFIED ENGLISH TRANSLATION OF APPLICATION

MAIL STOP MISSING PARTS
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant also submits herewith, in accordance with 37 C.F.R. §1.52(d), an English-language translation of the specification as filed on April 6, 2006, along with the Translator's Declaration executed on April 5, 2006.

No additional fees are believed due in connection with this filing. However, if it is determined otherwise, the Commissioner is hereby authorized to charge the undersigned's Deposit Account No. 50-0206.

Respectfully submitted,

HUNTON & WILLIAMS LLP

By: _____
Jeffrey Scott Leaning
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Dated: May 19, 2006
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